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FAIRCHILD
SEMICONDUCTOR TM

TN2219A
(TN2222A)

TO-226

NPN General Purpose Amplifier

This device is for use as a medium power amplifier and switch requiring collector currents up to 500 mA. Sourced from Process 19. See PN2222A for characteristics.

Absolute Maximum Ratings*

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{CEO}	Collector-Emitter Voltage	40	V
V_{CBO}	Collector-Base Voltage	75	V
V_{EBO}	Emitter-Base Voltage	6.0	V
I_C	Collector Current - Continuous	1.0	A
T_J, T_{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:
1) These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

TA = 25°C unless otherwise noted

Symbol	Characteristic	Max	Units
		TN2219A	
P_D	Total Device Dissipation Derate above 25°C	1.0 8.0	W W/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	50	°C/W

NPN General Purpose Amplifier
(continued)

Electrical Characteristics
TA = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
OFF CHARACTERISTICS					
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage*	I_C = 10 mA, I_B = 0	40		V
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage	I_C = 10 μA, I_E = 0	75		V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage	I_E = 10 μA, I_C = 0	6.0		V
I_{CEX}	Collector Cutoff Current	V_{CE} = 60 V, $V_{EB(OFF)}$ = 3.0 V		10	nA
I_{CBO}	Collector Cutoff Current	V_{CB} = 60 V, I_E = 0 V_{CB} = 60 V, I_E = 0, T_A = 150°C		10 10	nA μA
I_{EBO}	Emitter Cutoff Current	V_{EB} = 3.0 V, I_C = 0		10	nA
I_{BL}	Base Cutoff Current	V_{CE} = 60 V, $V_{EB(OFF)}$ = 3.0		20	nA
ON CHARACTERISTICS					
h_{FE}	DC Current Gain	I_C = 0.1 mA, V_{CE} = 10 V I_C = 1.0 mA, V_{CE} = 10 V I_C = 10 mA, V_{CE} = 10 V I_C = 150 mA, V_{CE} = 10 V I_C = 150 mA, V_{CE} = 1.0 V I_C = 500 mA, V_{CE} = 10 V	35 50 75 100 50 40	 300 	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage*	I_C = 150 mA, I_B = 15 mA I_C = 500 mA, I_B = 50 mA		0.3 1.0	V V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage*	I_C = 150 mA, I_B = 1.0 mA I_C = 500 mA, I_B = 5.0 mA	0.6	1.2 2.0	V V
SMALL SIGNAL CHARACTERISTICS					
C_{obo}	Output Capacitance	V_{CB} = 10 V, I_E = 0, f = 100 kHz		8.0	pF
C_{ibo}	Input Capacitance	V_{EB} = 0.5 V, I_C = 0, f = 100 kHz		25	pF
h_{fe}	Small-Signal Current Gain	I_C = 1.0 mA, V_{CE} = 10 V, f = 1.0 kHz I_C = 10 mA, V_{CE} = 10 V, f = 1.0 kHz	50 75	300 375	
rb'C_C	Collector Base Time Constant	I_E = 20 mA, V_{CB} = 20 V, f= 31.8 MHz		150	pS
NF	Noise Figure	I_C = 100 μA, V_{CE} = 10 V, R_S= 1.0 kΩ f = 1.0 kHz, B_W = 1.0 kHz		4.0	dB
Re(h_{ie})	Real Part of Common-Emitter High Frequency Input Impedance	I_C = 20 mA, V_{CE} = 20 V, f = 300 MHz		60	Ω
SWITCHING CHARACTERISTICS					
t_d	Delay Time	V_{CC} = 30 V, $V_{BE(OFF)}$ = 0.5 V,		10	ns
t_r	Rise Time	I_C = 150 mA, I_{B1} = 15 mA		25	ns
t_s	Storage Time	V_{CC} = 30 V, I_C = 150 mA,		225	ns
t_f	Fall Time	I_{B1} = I_{B2} = 15 mA		60	ns

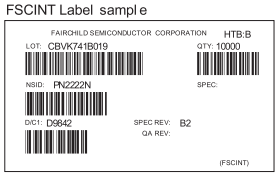
*Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

TO-226AE Tape and Reel Data

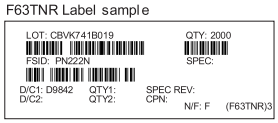
FAIRCHILD SEMICONDUCTOR™

TO-226AE Packaging
Configuration: Figure 1.0

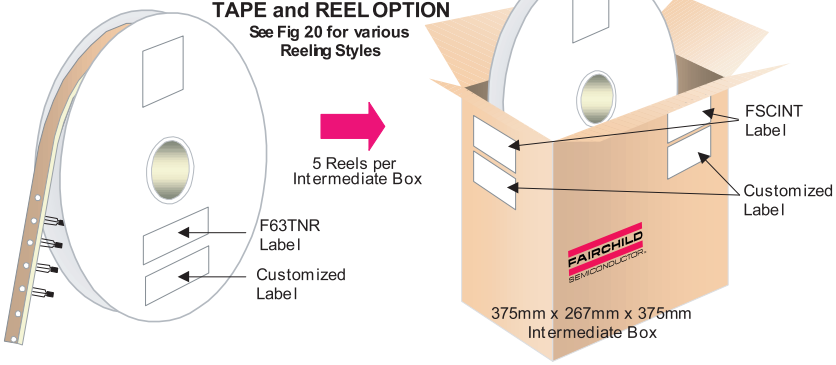
FSCINT Label sample



F63TNR Label sample



TAPE and REEL OPTION
See Fig 20 for various Reeling Styles

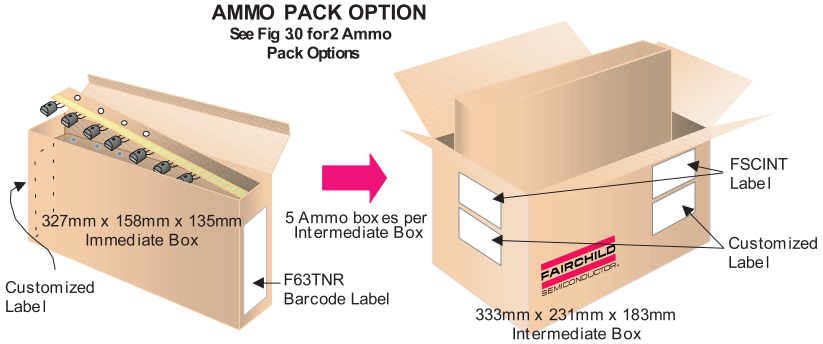


AMMO PACK OPTION
See Fig 30 for2 Ammo Pack Options

TO-226AE TNR/AMMO PACKING INFORMATION

Packing	Style	Quantity	EOL code
Reel	A	2,000	D26Z
	E	2,000	D27Z
Ammo	M	2,000	D74Z
	P	2,000	D75Z

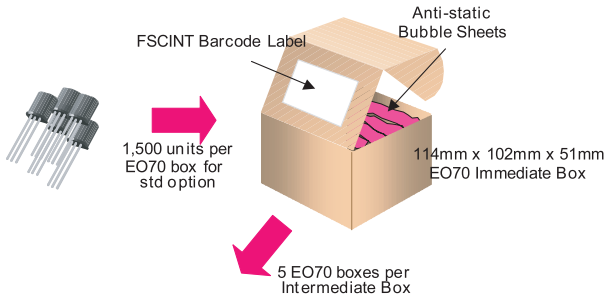
Unit weight = 0.300gm
Reel weight with components = 0.868 kg
Ammo weight with components = 0.880 kg
Max quantity per intermediate box = 10,000 units

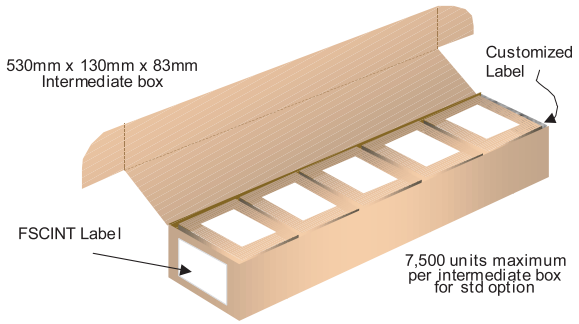


BULK OPTION
See Bulk Packing Information table

(TO-226AE) BULK PACKING INFORMATION

EOL CODE	DESCRIPTION	LEADCLIP DIMENSION	QUANTITY
J18Z	TO-18 OPTION STD	NO LEAD CLIP	1.0 K / BOX
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.0 K / BOX
NO EOL CODE	TO-226 STANDARD STRAIGHT	NO LEADCLIP	1.5 K / BOX

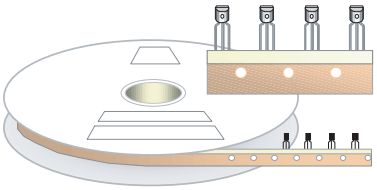




TO-226AE Tape and Reel Data, continued

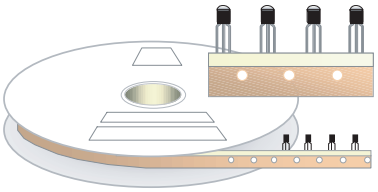
TO-226AE Reeling Style
Configuration: Figure 2.0

Machine Option "A" (H)



Style "A" D26Z, D70Z (s/h)

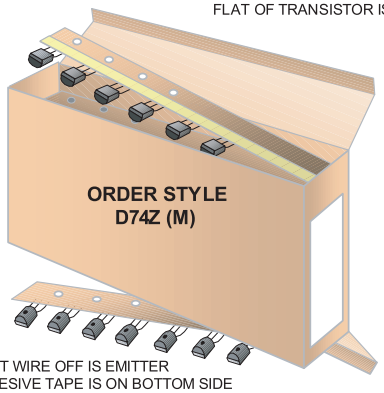
Machine Option "E" (J)



Style "E" D27Z, D71Z (s/h)

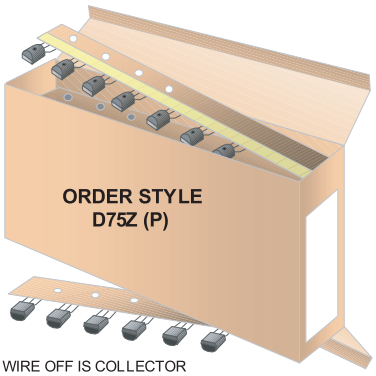
TO-226AE Radial Ammo Packaging
Configuration: Figure 3.0

FIRST WIRE OFF IS COLLECTOR (ON PKG. 92)
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON TOP



FIRST WIRE OFF IS EMITTER
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON BOTTOM

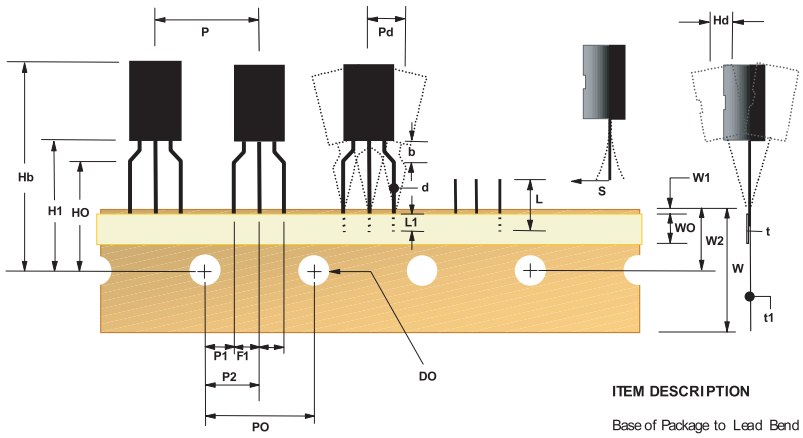
FIRST WIRE OFF IS EMITTER (ON PKG. 92)
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON BOTTOM



FIRST WIRE OFF IS COLLECTOR
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON TOP

TO-226AE Tape and Reel Data, continued

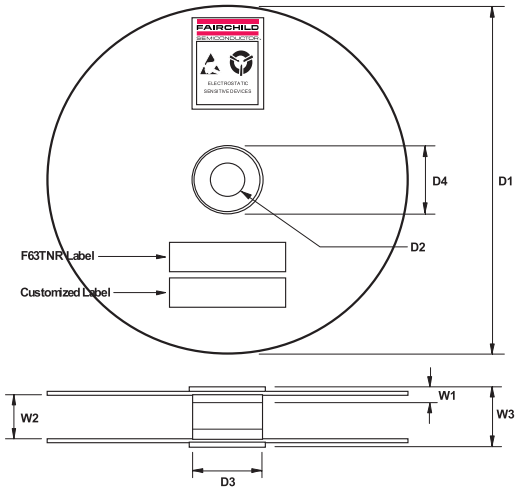
TO-226AE Tape and Reel Taping Dimension Configuration: Figure 4.0



ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	Hb	1.078 (+/- 0.050)
Lead Clinch Height	HO	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment (side/side)	Pd	0.040 (max)
Component Alignment (front/back)	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0.010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold-down Tape Width	WO	0.236 (+/- 0.012)
Hold-down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

Note: All dimensions are in inches.

TO-226AE Reel Configuration: Figure 5.0



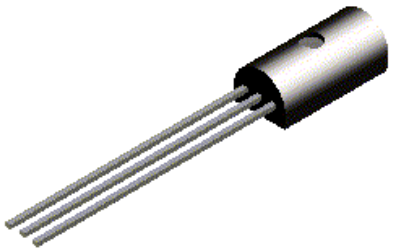
ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

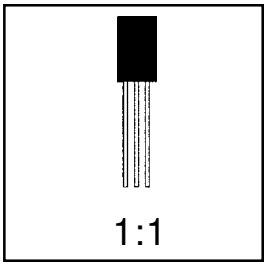
Note: All dimensions are inches

TO-226AE Package Dimensions

FAIRCHILD SEMICONDUCTOR™

TO-226AE (FS PKG Code 95, 99)

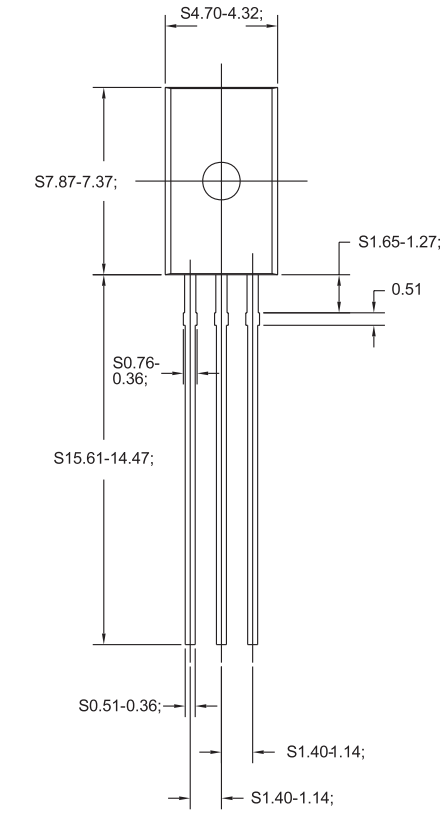


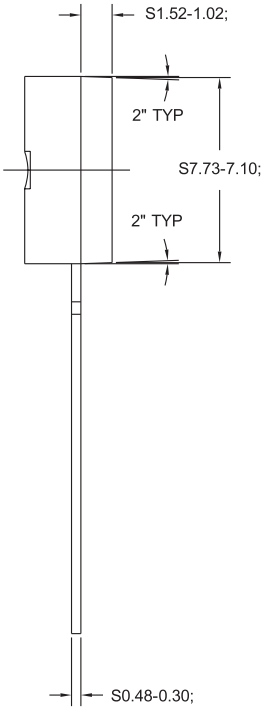


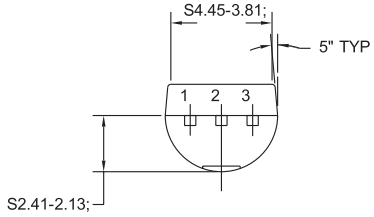
Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.300







PIN	99	95
1	E	E
2	B	C
3	C	B

TO-226AE (95,99)

For leadformed option ordering,
refer to Tape & Reel data information.

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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